

PACKAGE STRUCTURE, PACKAGING METHOD AND SEMICONDUCTOR DEVICE

ABSTRACT

Embodiments of disclosure provide a package structure, a packaging method and a semiconductor device. The packaging method includes: providing a semiconductor functional structure, in which an interconnecting layer is disposed on a surface of the semiconductor functional structure; forming an isolation layer exposing part of the interconnecting layer, in which the exposed part of the interconnecting layer acts as a first pad, and the first pad is used for performing a first type test; after completing the first type test, forming a redistribution layer on the first pad and the isolation layer, in which the redistribution layer and the interconnecting layer are electrically connected; and forming a first insulating layer exposing parts of the redistribution layer, in which the exposed parts of the redistribution layer act as a second pad and a third pad, the second pad is used for performing a second type test, and the third pad is used for executing a functional interaction corresponding to contents of the second type test, wherein a running speed of the semiconductor functional structure when performing the first type test is lower than a running speed when performing the second type test.

[Fig. 1]